

2023/10

ADEKA REMYLOP FL-288

Product Features

- One-component heat curing adhesive
- Rapid curing type
- Low elasticity (stress relaxation, impact resistance, adhesion of different materials)
- Epoxy type (Halogen-free available)
- NIR laser curable

Properties (uncured)

Viscosity / 25°C	2 ⁻¹ 20 ⁻¹	13 7	Pa · s Pa · s
Thixotropic value	2 ⁻¹ /20 ⁻¹	1.8	
Specific gravity		1.13	
Filler content		< 5	wt %
Nonvolatile content		> 99	%
Pot Life	25 °C	> 24	hrs
Shelf Life	≤ -20 °C	> 180	days

Cured Material Properties

Glass transition temperature	TMA DMA	17 28	°C °C
Hardness	ShoreD	—	
Storage modulus/ 25°C	DMA	0.1	GPa
Coefficient of linear expansion	α _l	75	ppm
Thermal conductivity	非定常法	< 0.2	W/m · K
Curing shrinkage	密度測定法	2.9	%

DSC : SHI DCS6220 25 – 250 °C (10 °C/min)

DMA : TA RSA-G2 -50 – 250 °C (10 °C/min),
curing condition ; 125 °C × 1 hr

TMA : SHI TMA/SS6100 -55 – 150 °C (5 °C/min),
curing condition ; 125 °C × 1 hr

Thermal conductivity : C-Therm Tci, curing condition ; 125 °C × 1 hr

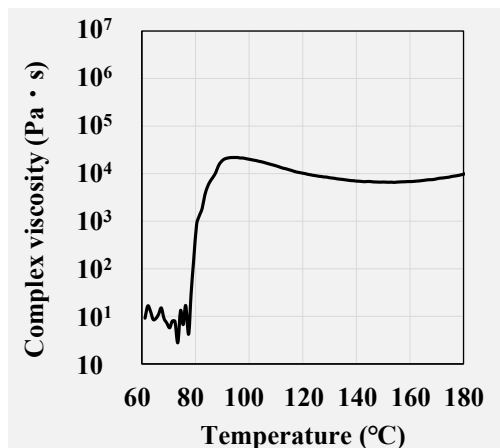
Recommended Curing Conditions

125 °C

1.0 hr

Lase curing condition (e.g.) : 940 nm, 4 mmφ, 3 W, 3 sec.

Curing behavior



Usage

【Storage】 Store frozen (below -20 °C)

【Breaking the seal】 To prevent moisture condensation, please bring the product to room temperature before opening the package.

Recommended defrosting time : Syringe ; 25 °C, 1 h or more.

Barrel ; 25 °C, 2 h or more.

【Curing】 When curing more than 1 g, please be careful of runaway reactions.

【Disposal】 Please refer to SDS for proper treatment.

【Others】 Please contact us at the following

株式会社 ADEKA

Group-3 Commodity Materials Department Chemicals Division

Tell 03-4455-2843

Mail adeka-adhesive.official@adeka.co.jp